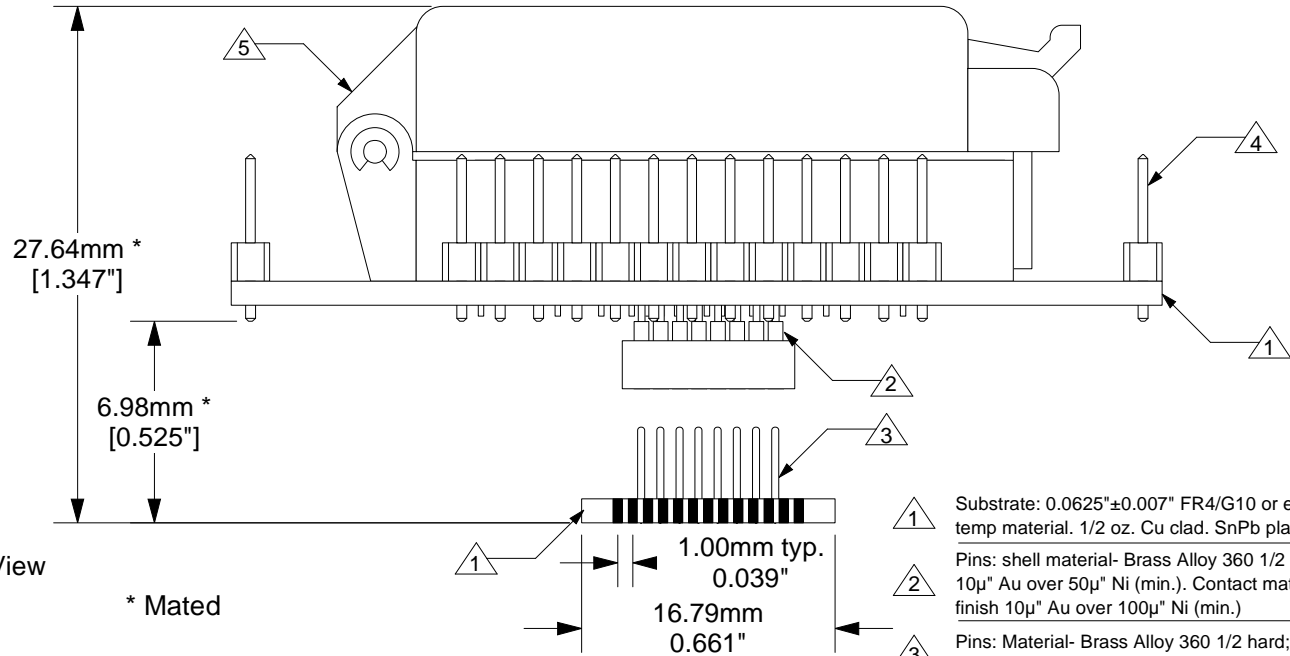


Top View




Side View

* Mated

- 1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- 2 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.)
- 3 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- 4 Test points: material- Phosphor Bronze; plating- Sn over 50µ" Ni. Gold flash on contact end.
- 5 Socket Contacts: base: material- Beryllium Copper; plating- Au over Ni.

Description: Carrier Adaptor (CA), QFP
 52 position QFP ZIF socket with test points and pluggable intermediate interface compatible with SF-QFE52SF-L-03 surface-mount foot (lead-less) shown (not included).

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

CA-QFE52SF-M-Z-T-01 Drawing		Status: Released	Scale: 2:1	Rev: A
 © 2000 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: P Jasmin		Date: 1/5/00	
	File: CA-QFE52SF-M-Z-T-01 Dwg		Modified:	